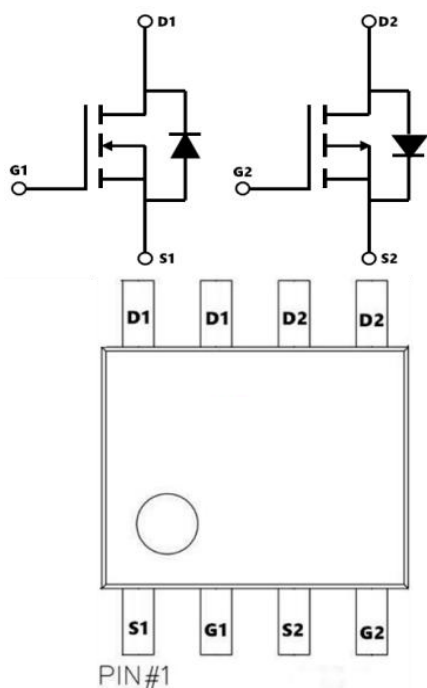


Description

The SX10G04S uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



General Features

$V_{DS} = 40V$ $I_D = 9.8A$

$R_{DS(ON)} < 22m\Omega$ @ $V_{GS}=10V$

$V_{DS} = -40V$ $I_D = -8.5A$

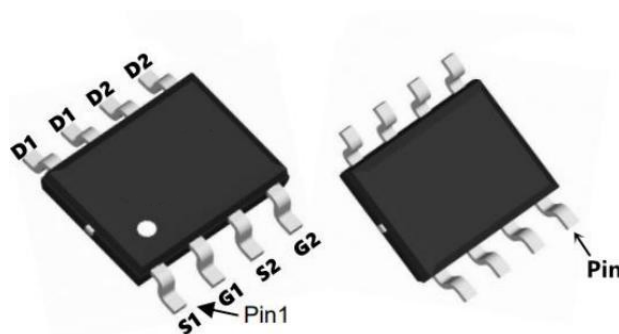
$R_{DS(ON)} < 38m\Omega$ @ $V_{GS}=-10V$

Application

Wireless charging

Boost driver

Brushless motor



Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V_{DS}	Drain-Source Voltage	40	-40	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V ¹	9.8	-8.5	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, V_{GS} @ 10V ¹	5.2	-4.8	A
I_{DM}	Pulsed Drain Current ²	23	-22	A
E_{AS}	Single Pulse Avalanche Energy ³	16.2	39	mJ
I_{AS}	Avalanche Current	18	-28	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation ⁴	1.67	1.67	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	75		$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	30		$^\circ C/W$

N-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40	44	---	V
ΔBVDSS/ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA	---	0.034	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =5A	---	16	22	mΩ
		V _{GS} =4.5V , I _D =4A	---	18	28	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.6	2.5	V
ΔVGS(th)	VGS(th) Temperature Coefficient		---	-4.56	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =32V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =32V , V _{GS} =0V , T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A	---	14	---	S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	2.6	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =20V , V _{GS} =4.5V , I _D =5A	---	5.5	---	nC
Q _{gs}	Gate-Source Charge		---	1.25	---	
Q _{gd}	Gate-Drain Charge		---	2.5	---	
Td(on)	Turn-On Delay Time	V _{DD} =20V , V _{GS} =10V , R _G =3.3Ω I _D =1A	---	8.9	---	ns
T _r	Rise Time		---	2.2	---	
Td(off)	Turn-Off Delay Time		---	41	---	
T _f	Fall Time		---	2.7	---	
C _{iss}	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz	---	593	---	pF
C _{oss}	Output Capacitance		---	76	---	
C _{rss}	Reverse Transfer Capacitance		---	56	---	
I _s	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	---	---	6.1	A
ISM	Pulsed Source Current ^{2,5}		---	---	23	A
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C	---	---	1.2	V

Note :

- 1、 The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=10A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5 、 The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	-40	-44	---	V
$\Delta BVDSS/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1mA$	---	-0.02	---	V/ $^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=-10V$, $I_D=-6A$	---	31	38	m Ω
		$V_{GS}=-4.5V$, $I_D=-3A$	---	43	53	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu A$	-1.0	-1.6	-2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3.72	---	mV/ $^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-32V$, $V_{GS}=0V$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=-32V$, $V_{GS}=0V$, $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=-5V$, $I_D=-6A$	---	13	---	S
Qg	Total Gate Charge (-4.5V)	$V_{DS}=-20V$, $V_{GS}=-4.5V$, $I_D=-6A$	---	11.5	---	nC
Qgs	Gate-Source Charge		---	3.5	---	
Qgd	Gate-Drain Charge		---	3.3	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-15V$, $V_{GS}=-10V$, $R_G=3.3\Omega$, $I_D=-1A$	---	22	---	ns
Tr	Rise Time		---	15.7	---	
Td(off)	Turn-Off Delay Time		---	59	---	
Tf	Fall Time		---	5.5	---	
Ciss	Input Capacitance	$V_{DS}=-15V$, $V_{GS}=0V$, $f=1MHz$	---	1415	---	pF
Coss	Output Capacitance		---	134	---	
Crss	Reverse Transfer Capacitance		---	102	---	
Is	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current	---	---	-6	A
ISM	Pulsed Source Current ^{2,5}		---	---	-22	A
VSD	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=-1A$, $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating. The test condition is $V_{DD}=-25V$, $V_{GS}=-10V$, $L=0.1mH$, $I_{AS}=-10A$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

N-Channel Typical Characteristics

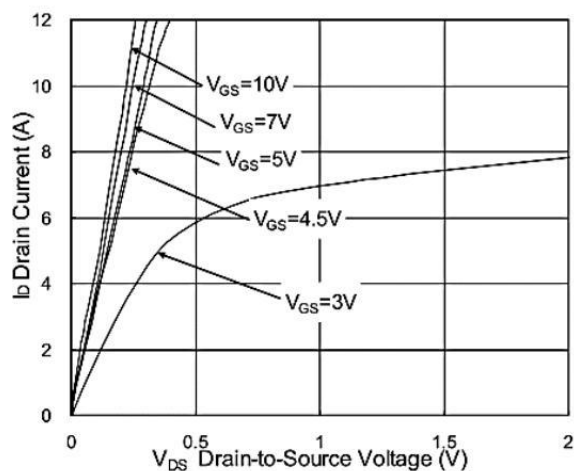


Fig.1 Typical Output Characteristics

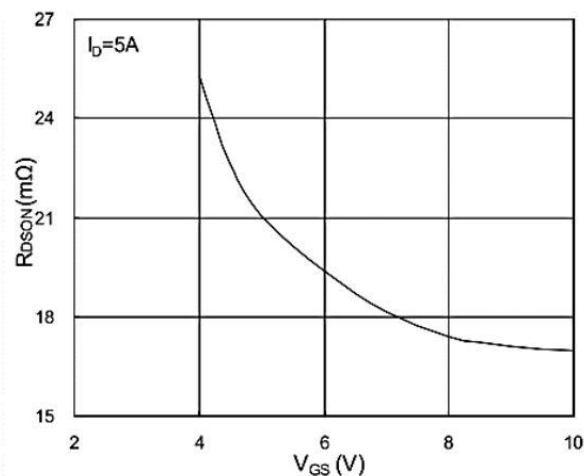


Fig.2 On-Resistance vs. G-S Voltage

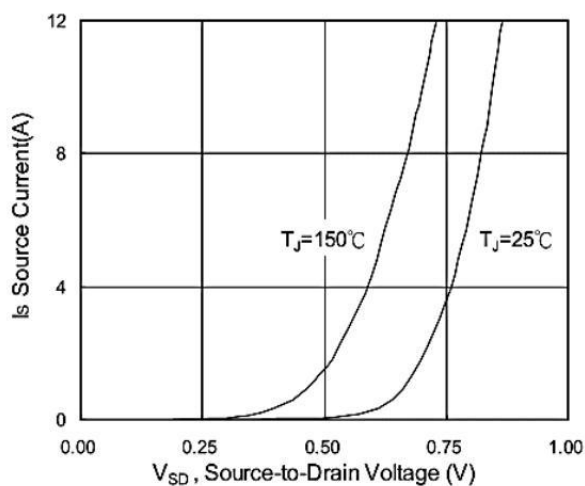


Fig.3 Source Drain Forward Characteristics

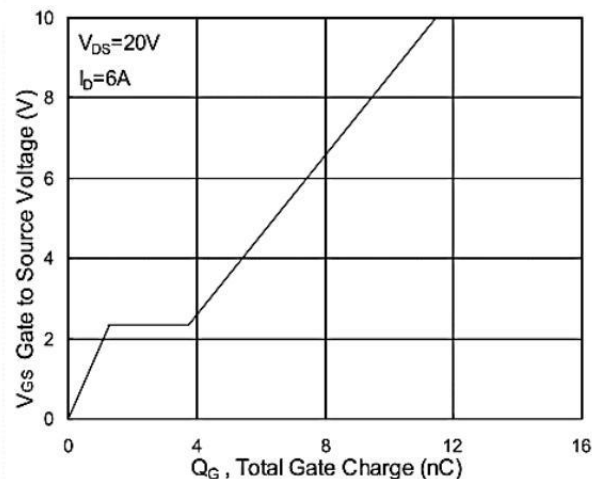


Fig.4 Gate-Charge Characteristics

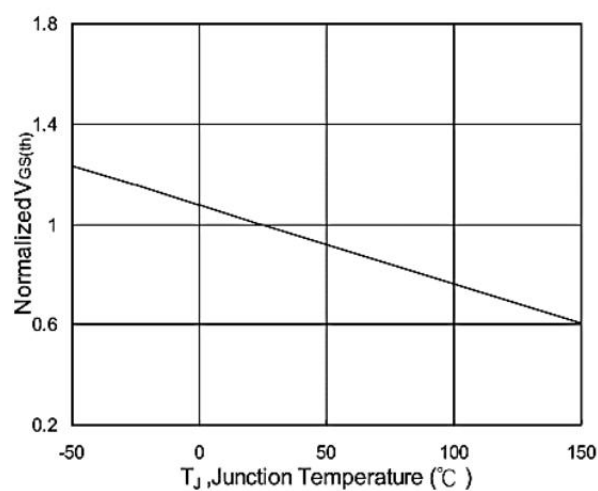


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

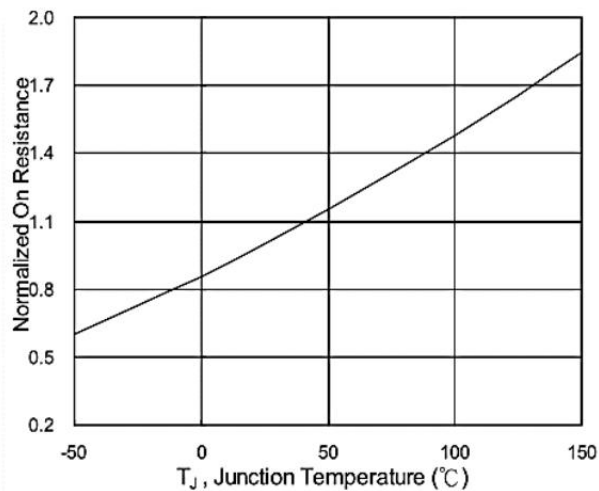


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

N-Channel Typical Characteristics

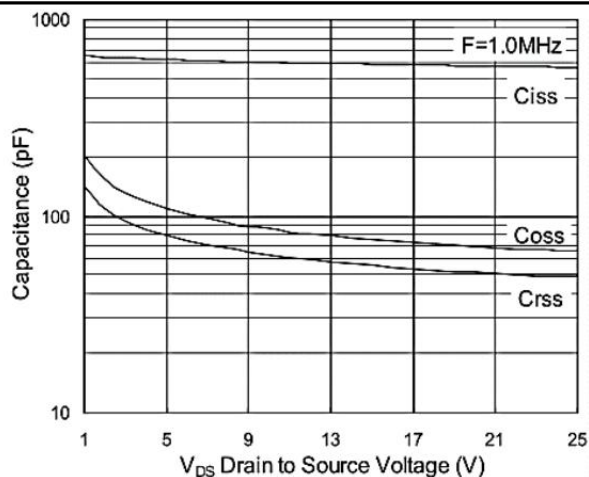


Fig.7 Capacitance

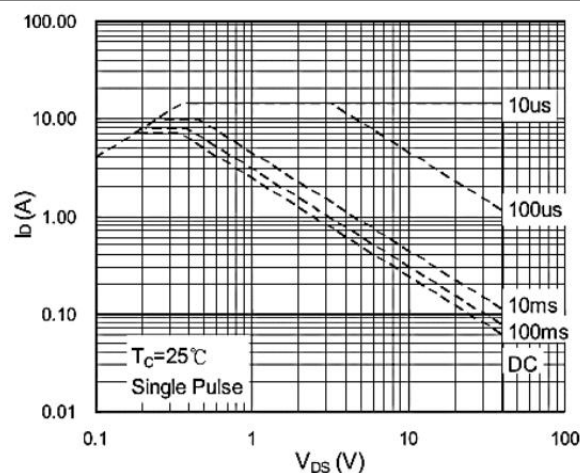


Fig.8 Safe Operating Area

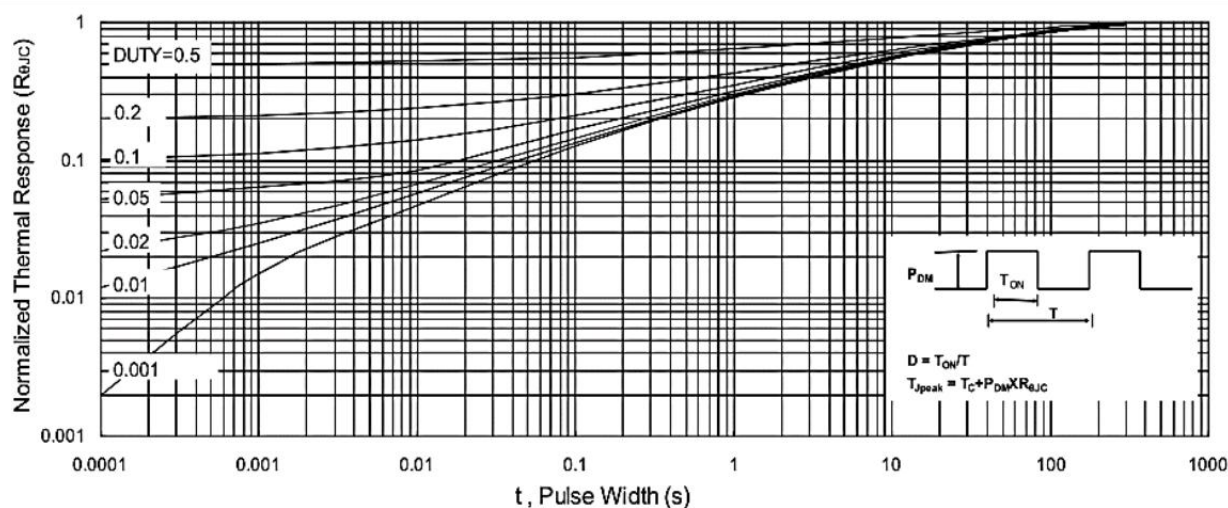


Fig.9 Normalized Maximum Transient Thermal Impedance

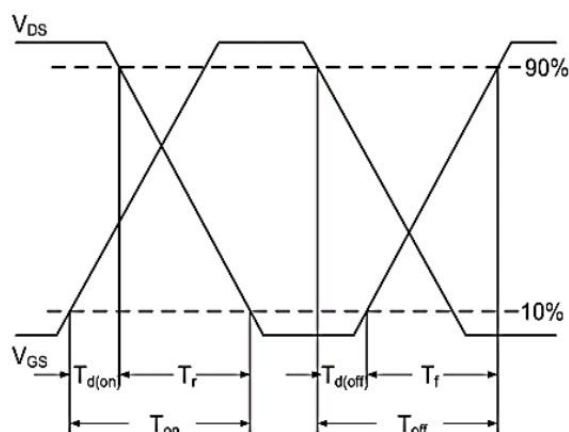


Fig.10 Switching Time Waveform

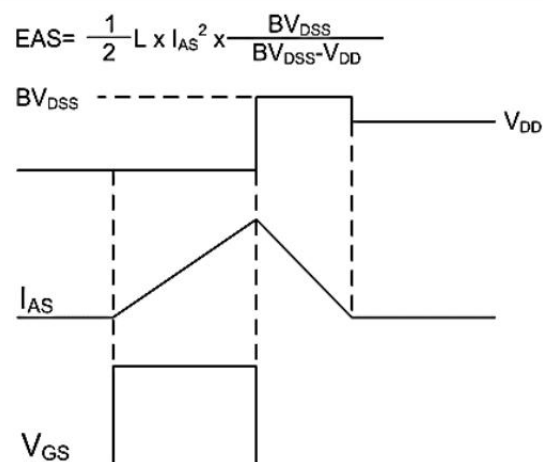


Fig.11 Unclamped Inductive Waveform

P-Channel Typical Characteristics

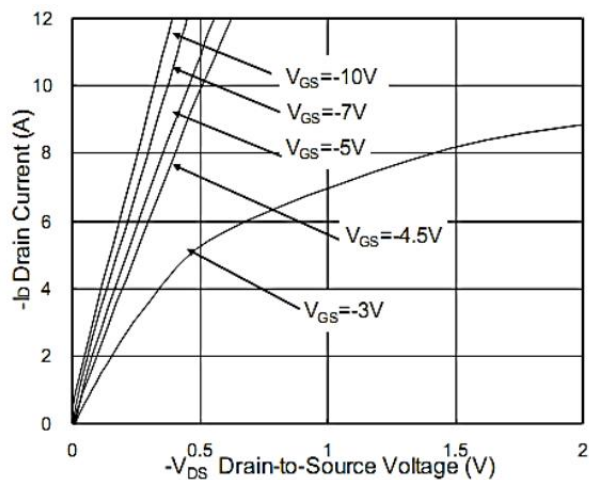


Fig.1 Typical Output Characteristics

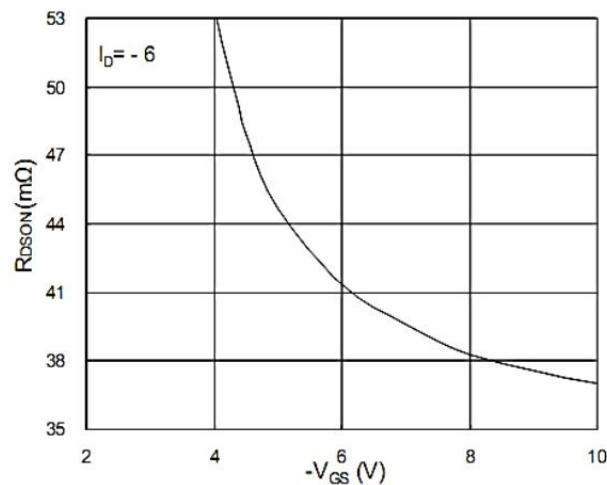


Fig.2 On-Resistance vs. G-S Voltage

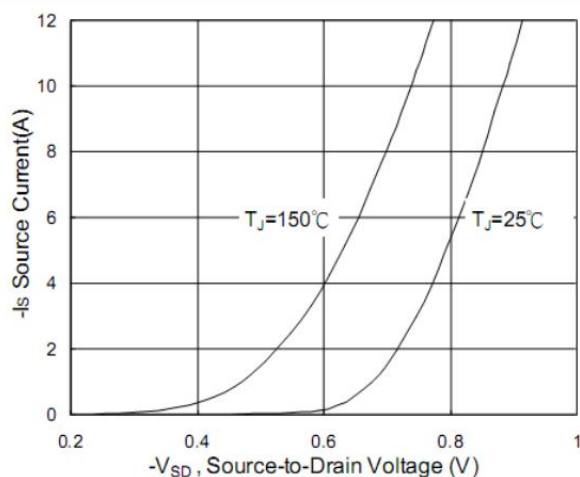


Fig.3 Source Drain Forward Characteristics

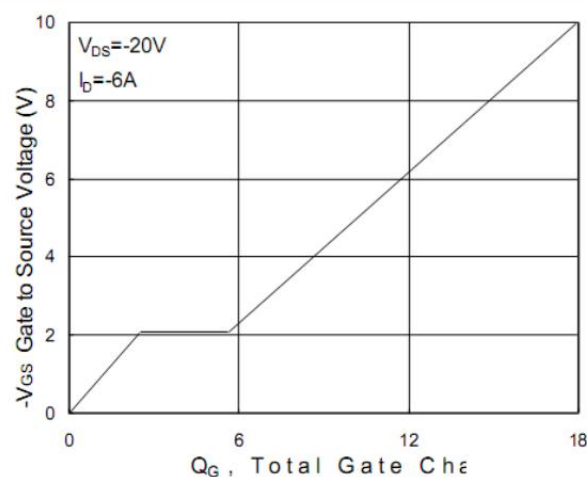


Fig.4 Gate-Charge Characteristics

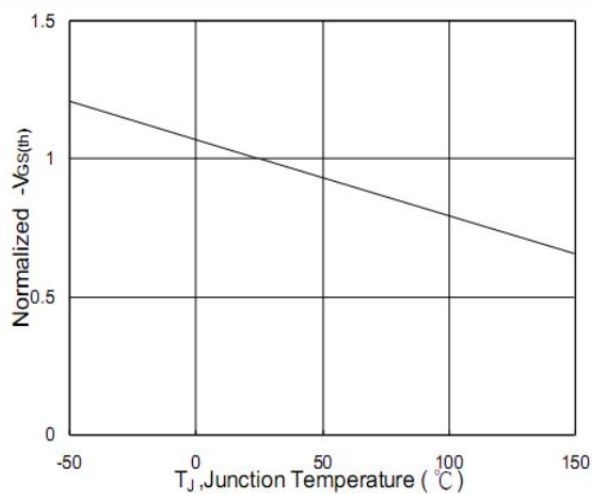


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

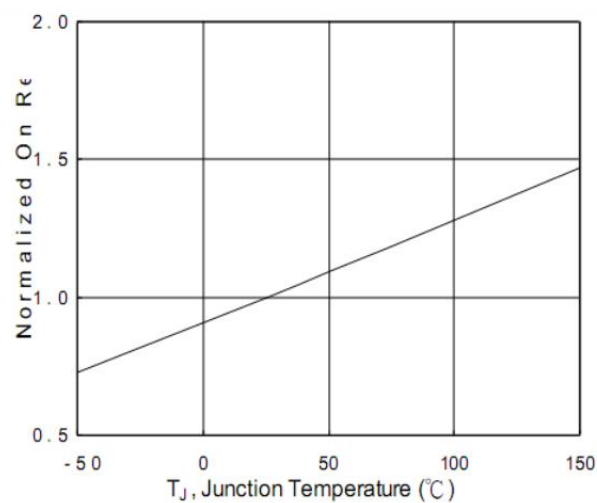


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

P-Channel Typical Characteristics

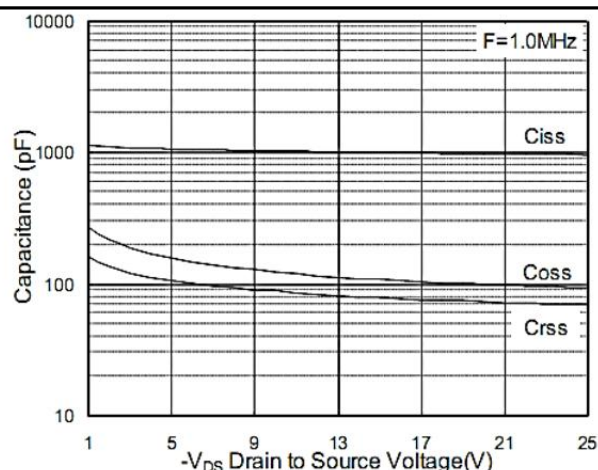


Fig.7 Capacitance

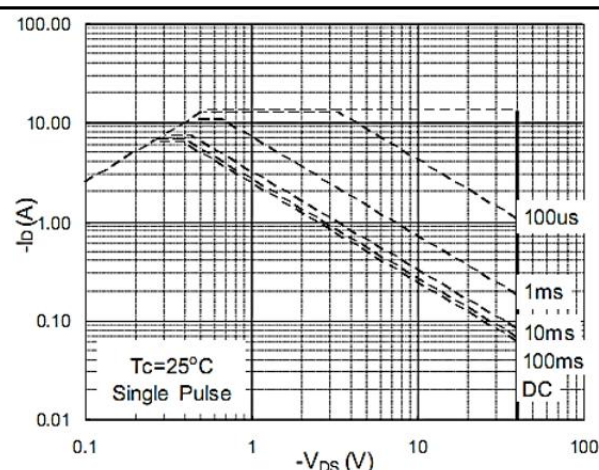


Fig.8 Safe Operating Area

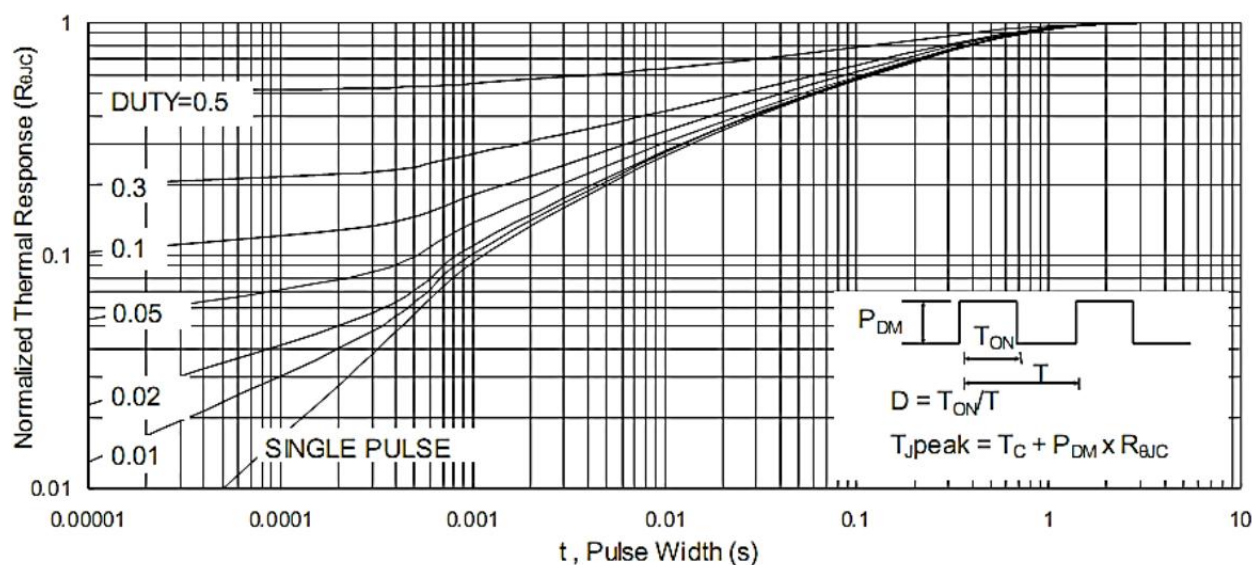


Fig.9 Normalized Maximum Transient Thermal Impedance

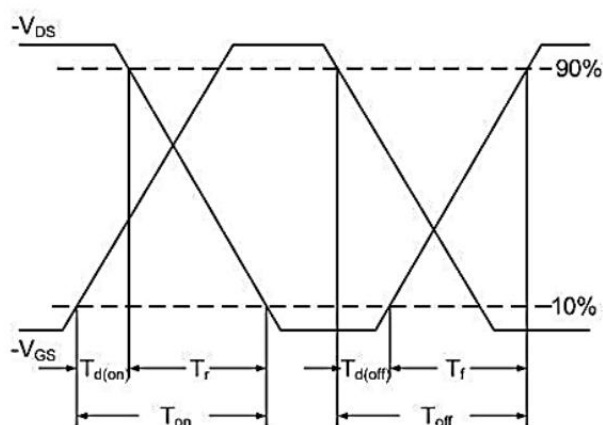


Fig.10 Switching Time Waveform

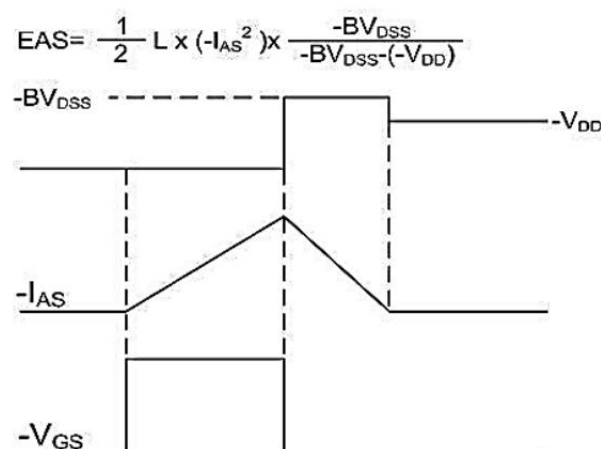
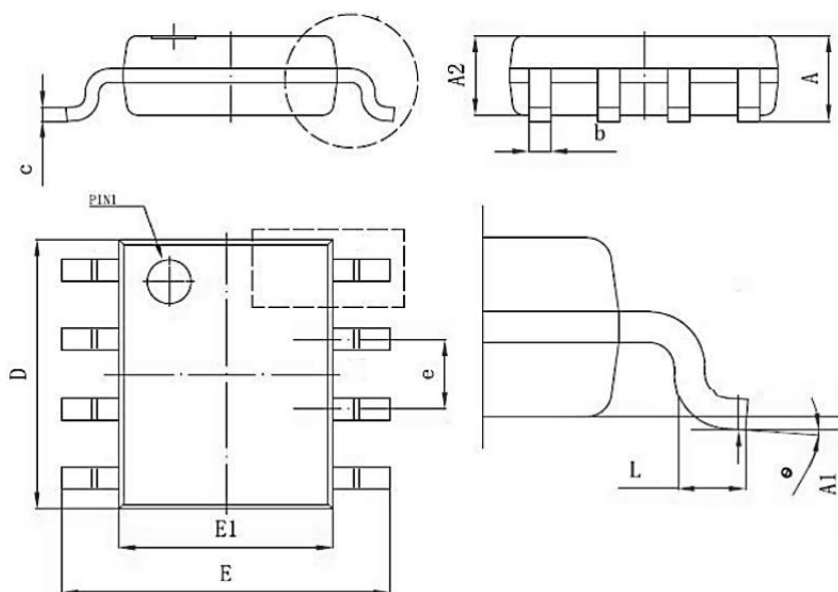


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-SOP-8L



Symbol	Dim in mm		
	Min	Typ	Max
A	1.35	1.55	1.75
A1	0.02	0.15	0.25
A2	1.425	1.45	1.475
b	0.3	0.4	0.5
c	0.15	0.2	0.25
D	4.8	5	5.2
E	5.8	6	6.2
E1	3.8	4	4.2
e	1.27BSC		
L	0.4		1.27
θ	0°		8°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOP-8L		3000